

PMP4394 BOM

Nov.15, 2013

| Item | Qty | Reference | Description | Size | Value | MFR |
|------|-----|-----------|--|---------|----------------|--------|
| 1 | 1 | C20 | Capacitor, Ceramic | 0603 | 0.01uF/25V | STD |
| 2 | 1 | C44 | Capacitor, Ceramic | 0603 | 0.1uF/50V | STD |
| 3 | 1 | C22 | Capacitor, Ceramic | 0603 | 1uF/16V | STD |
| 4 | 1 | C1 | Capacitor, Ceramic | 0603 | 3.3nF/50V | STD |
| 5 | 1 | C50 | Capacitor, Ceramic | 0603 | NA | STD |
| 6 | 2 | C2 C4 | Capacitor, Ceramic | 0805 | 10uF/6.3V | STD |
| 7 | 1 | C7 | Capacitor, Ceramic | 0805 | 1uF/35V | STD |
| 8 | 1 | C6 | Capacitor, Ceramic | 0805 | 2.2uF/16V | STD |
| 9 | 2 | C3 C5 | Capacitor, Ceramic | 0805 | NA | STD |
| 10 | 1 | J1 | 100mil connector | | | STD |
| 11 | 1 | D3 | Diode, Schottky, 75V, 0.25A, SOD-323 | SOD-323 | 1N4148WS | STD |
| 12 | 1 | U12 | 48V, 325mA Wide Vin Synchronous Step-down Regulator with Integrated MOSFETs | WS0N-8 | LM25018SD/NOPB | TI |
| 13 | 1 | T1 | Transformer, MTC-0018SG | | | MNC |
| 14 | 1 | R3 | Resistor, Chip, 1/10W, 1% | 0603 | 10K | STD |
| 15 | 1 | R34 | Resistor, Chip, 1/10W, 1% | 0603 | 11K | STD |
| 16 | 1 | R69 | Resistor, Chip, 1/10W, 1% | 0603 | 20K | STD |
| 17 | 1 | R32 | Resistor, Chip, 1/10W, 1% | 0603 | 240K | STD |
| 18 | 1 | R5 | Resistor, Chip, 1/10W, 1% | 0603 | 4.3K | STD |
| 19 | 1 | R33 | Resistor, Chip, 1/10W, 1% | 0603 | 62K | STD |
| 20 | 3 | R4 R1-R2 | Resistor, Chip, 1/10W, 1% | 0603 | NA | STD |
| 21 | 2 | D1-2 | DIODE SCHOTTKY 40V 0.4A SOD323 | SOD-323 | ZHCS400 | Diodes |
| 22 | 2 | D4 D5 | Diode, Zener, 5.6V, 400mW, SOD-323 | SOD-323 | 5.6V | STD |

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